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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/591,134	08/30/2006	Hiroshi Yamada	Q95305	7348
23373 7590 12/03/2008 SUGHRUE MION, PLLC 2100 PENNSYLVANIA AVENUE, N.W.			EXAMINER	
			PAPE, ZACHARY	
SUITE 800 WASHINGTOI	ASHINGTON, DC 20037		ART UNIT	PAPER NUMBER
			2835	
			MAIL DATE	DELIVERY MODE
			12/03/2008	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)
	10/591,134	YAMADA ET AL.
Office Action Summary	Examiner	Art Unit
	ZACHARY M. PAPE	2835
The MAILING DATE of this communication ap Period for Reply	opears on the cover sheet with the	correspondence address
A SHORTENED STATUTORY PERIOD FOR REPOWHICHEVER IS LONGER, FROM THE MAILING IF Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory perior. Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNICATIO .136(a). In no event, however, may a reply be tid d will apply and will expire SIX (6) MONTHS fron the, cause the application to become ABANDONI	N. mely filed n the mailing date of this communication. ED (35 U.S.C. § 133).
Status		
Responsive to communication(s) filed on 19. This action is FINAL . 2b) ☐ This action is FINAL . Since this application is in condition for allow closed in accordance with the practice under	is action is non-final. ance except for formal matters, pr	
Disposition of Claims		
4) Claim(s) 1-7 is/are pending in the application 4a) Of the above claim(s) is/are withdrest is/are allowed. 5) Claim(s) is/are allowed. 6) Claim(s) 1 and 2 is/are rejected. 7) Claim(s) 3-7 is/are objected to. 8) Claim(s) are subject to restriction and/	awn from consideration.	
9) The specification is objected to by the Examir	ner	
10) ☐ The drawing(s) filed on 30 August 2006 is/are Applicant may not request that any objection to the Replacement drawing sheet(s) including the corre 11) ☐ The oath or declaration is objected to by the E	e: a)⊠ accepted or b)⊡ objected e drawing(s) be held in abeyance. Se ction is required if the drawing(s) is ob	ee 37 CFR 1.85(a). ojected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Burest * See the attached detailed Office action for a list	nts have been received. nts have been received in Applicat ority documents have been receiv au (PCT Rule 17.2(a)).	ion No ed in this National Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal I 6) Other:	oate

DETAILED ACTION

The following detailed action is in response to the correspondence filed 9/19/2008.

Specification

The objection to the abstract has been withdrawn in view of the amendment thereto.

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-2 are rejected under 35 U.S.C. 103(a) as being unpatentable over Masashi et al. (JP 2002111250 - provided by Applicants, hereinafter, "Masashi") in view of Kledzik et al. (US 6,487,078 - hereinafter, "Kledzik").

With respect to claim 1, Masashi teaches (In Fig 1)a modular heat-radiation structure comprising: a printed circuit board (111); a module (121)for generating heat, including a first main unit having a fixing hole (That which 161 engages) and a lead (171) for connecting to the printed circuit board; a heat-radiation fin (131), fixed to the top face of the first main unit, for radiating heat generated in the module; an insulating heat shield (141) inserted between the printed circuit board and the first main unit; and a

fixing element (161) for fixing the heat shield, the module, and the heat-radiation fin; wherein: a first fixing hole (181) for allowing the fixing element to pass therethrough are provided in the heat shield, and a second fixing hole for allowing the fixing element to pass therethrough is provided in the printed circuit board (See Fig 1). Masashi fails to teach or suggest that the heat shield is resin-made and includes a lead hole for allowing the lead to pass therethrough. Kledzik teaches (In Fig 5) the conventionality of having a heat shield (101) which is resin-made (Col 4, Lines 52-55) and has a lead hole (106) for allowing a lead (502) to pass therethrough (See also Fig 6). It would have been obvious to one of ordinary skill in the art at the time the invention was made to combine the aforementioned teachings of Kledzik with that of Masashi to provide protection for the leads (Instead of the leads being exposed as per the teachings of Masashi, the leads would be at least partially protected).

With respect to claim 2, Kledzik further teaches a chip (507) fixed onto the printed circuit board (503) and mounted under the first main unit (See Fig 5), wherein: either a slit or a concave (Concave portion in the end of the heat shield) for inserting the chip is formed in the heat shield.

Allowable Subject Matter

2. Claims 3-7 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

See the Official Action dated 6/19/2008.

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Response to Arguments

3. Applicant's arguments filed 9/19/2008 have been fully considered but they are not persuasive.

With respect to the Applicants' remarks to claim 1 that, "neither Masashi nor Kledzik teach the use of a resin-made and insulating heat shield inserted between the printed circuit board and the first main unit", the Examiner respectfully disagrees. Kledzik, at Col 4, Lines 52-55 teaches that the heat shield (101) is made of a resin ("fiberglass-reinforced plastic").

With respect to the Applicants' remarks regarding the term, "heat shield" (versus, "fixing spacer" (Masashi) and "dielectric body" (Kledzik)), the Examiner respectfully notes that both elements 141 and 101 of Masashi and Kledzik, respectfully, act as a "heat shield" since they provide some level of resistance to the heat by shielding the components from conduction, convection, radiation and/or any combination thereof.

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to ZACHARY M. PAPE whose telephone number is (571)272-2201. The examiner can normally be reached on Mon.- Fri. 8am - 5pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Jayprakash Gandhi can be reached on 571-272-3740. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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/Zachary M Pape/ Examiner, Art Unit 2835